Features

- Input Frequency Range 2.7 GHz to 3.0 GHz
- P_{OUT} Typically 12 dBm at 5.8 GHz
- P_{IN} Typically 0 dBm
- V_{cc} 3.0V to 3.9V
- CW Mode Operation
- Package: QFN16

Benefits

- Ramping Control Extends Battery Lifetime
- AC Input Coupling Saves External Capacitors
- Extremely Low BOM for Application

Electrostatic sensitive device. Observe precautions for handling.



1. Description

The 5.8-GHz frequency doubler IC is designed with Atmel's Silicon-Germanium (SiGe) process and provides a high conversion gain.

The device consists of a doubler stage, a filter and a driver amplifier with an output power of 11 dBm. The output stage was realized using an open-collector structure. Power-up/down and output levels are controlled via the bias control pin 6 and pin 7 (V_{CTL}).







2.9 GHz to 5.8 GHz SiGe Frequency Doubler IC

ATR7039

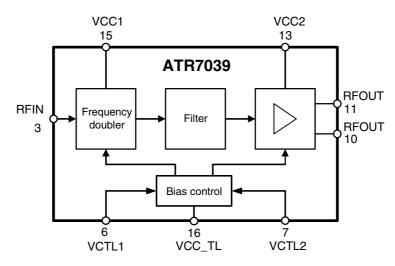
Preliminary

Rev. 4786E-DECT-10/05





Figure 1-1. Block Diagram



2. Pin Configuration

Figure 2-1. Pinning QFN16

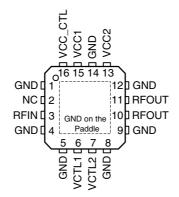


Table 2-1.	2-1. Pin Description					
Pin	Symbol	Function				
1	GND	Ground				
2	NC	Not connected				
3	RFIN	RF input				
4	GND	Ground				
5	GND	Ground				
6	VCTL1	Power-up/biasing control voltage to frequency doubler stage				
7	VCTL2	Power-up/biasing control voltage to output amplifier stage				
8	GND	Ground				
9	GND	Ground				
10	RFOUT	RF output				
11	RFOUT	RF output				
12	GND	Ground				
13	VCC2	Supply voltage for output amplifier stage				
14	GND	Ground				
15	VCC1	Supply voltage for frequency doubler stage				
16	VCC_CTL	Supply voltage for biasing control				
Paddle	-	Ground				





3. Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Parameters	Symbol	Value	Unit
Supply voltage, no RF	V _{CC}	5	V
Supply current	I _{CC}	400	mA
Junction temperature	Tj	150	°C
Storage temperature	T _{Stg}	-40 to +125	°C
Input RF power	P _{IN}	13	dBm
Control voltage	V _{CTL1,2}	2.5	V

Note: The part may not survive all parameters at maximum applied simultaneously!

4. Thermal Resistance

Parameters	Symbol	Value	Unit
Junction ambient QFN16 package, slug soldered on PCB	R _{thJA}	40	K/W

5. Operating Range

Parameters	Symbol	Value	Unit
Supply voltage	V _{CC}	3.0 to 3.9	V
Input frequency range	f _{in}	2700 to 3000	MHz
Output frequency range	f _{out}	5400 to 6000	MHz
Ambient temperature range	T _{amb}	-25 to +75	°C

6. Electrical Characteristics

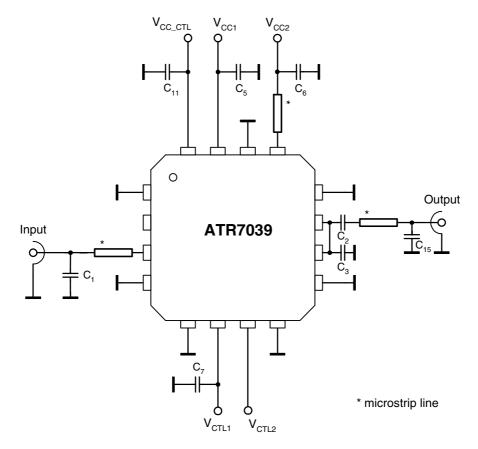
No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Type*
1.0	Input power		3	Pin		0	10	dBm	A
1.1		Measured at harmonic frequency 2f	10, 11	P2f		12		dBm	А
1.2	Output power	Measured at harmonic frequency 3f	10, 11	P3f		-8		dBm	A
1.3		Measured at fundamental frequency	10, 11	P1f		TBD		dBm	A
1.4	Output power deviation	Measured at harmonic frequency	10, 11	P _d	-2		+2	dB	A
15		Doubler operating	6	V _{CTL1}		1.4		V	А
1.5	1.5 Control voltage range	mode	7	V _{CTL2}		1.7		V	А
1.6		Power down mode	6, 7	V _{CTL1,2}			0.2	V	А
1.7	Input and output return loss	With external matching	3, 10, 11			-12	-8	dB	С
1.8	Reverse isolation	2f	3, 10, 11	ISO _r	30	36		dB	С
1.9	Current consumption	for 12dBm output power	13, 15, 16	I _{CC}		90		mA	A
1.10	Current consumption in power down mode	V _{CTL1,2} ≤0.2V	13, 15, 16	I _{CC}		15		μA	A
2.0	Duty cycle						100	%	С

*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter





7. Application Circuit



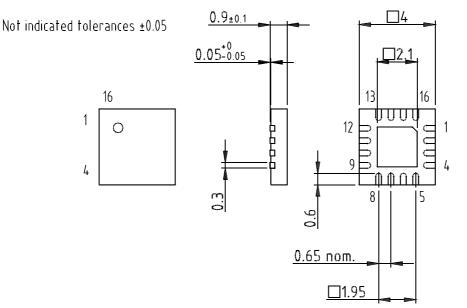
ATR7039 [Preliminary]

8. Ordering Information

Extended Type Number	Package	Remarks
ATR7039-PESG	QFN16 - 4x4	Tube, MOQ 750, Pb-free
ATR7039-PEQG	QFN16 - 4x4	Taped and reeled, MOQ 6000, Pb-free

9. Package Information

Package: QFN 16 - 4x4 Exposed pad 2.1x2.1 (acc. JEDEC OUTLINE No. MO-220) Dimensions in mm





technical drawings according to DIN specifications

Drawing-No.: 6.543-5090.01-4 Issue: 2; 24.01.03





Atmel Corporation

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 487-2600

Regional Headquarters

Europe

Atmel Sarl Route des Arsenaux 41 Case Postale 80 CH-1705 Fribourg Switzerland Tel: (41) 26-426-5555 Fax: (41) 26-426-5500

Asia

Room 1219 Chinachem Golden Plaza 77 Mody Road Tsimshatsui East Kowloon Hong Kong Tel: (852) 2721-9778 Fax: (852) 2722-1369

Japan

9F, Tonetsu Shinkawa Bldg. 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033 Japan Tel: (81) 3-3523-3551 Fax: (81) 3-3523-7581

Atmel Operations

Memory 2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

Microcontrollers

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

La Chantrerie BP 70602 44306 Nantes Cedex 3, France Tel: (33) 2-40-18-18-18 Fax: (33) 2-40-18-19-60

ASIC/ASSP/Smart Cards

Zone Industrielle 13106 Rousset Cedex, France Tel: (33) 4-42-53-60-00 Fax: (33) 4-42-53-60-01

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906, USA Tel: 1(719) 576-3300 Fax: 1(719) 540-1759

Scottish Enterprise Technology Park Maxwell Building East Kilbride G75 0QR, Scotland Tel: (44) 1355-803-000 Fax: (44) 1355-242-743

RF/Automotive

Theresienstrasse 2 Postfach 3535 74025 Heilbronn, Germany Tel: (49) 71-31-67-0 Fax: (49) 71-31-67-2340

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906, USA Tel: 1(719) 576-3300 Fax: 1(719) 540-1759

Biometrics/Imaging/Hi-Rel MPU/

High Speed Converters/RF Datacom Avenue de Rochepleine BP 123 38521 Saint-Egreve Cedex, France Tel: (33) 4-76-58-30-00 Fax: (33) 4-76-58-34-80

Literature Requests www.atmel.com/literature

Disclaimer: The information in this document is provided in connection with Atmel products. No license, express or implied, by estoppel or otherwise, to any intellectual property right is granted by this document or in connection with the sale of Atmel products. EXCEPT AS SET FORTH IN ATMEL'S TERMS AND CONDI-TIONS OF SALE LOCATED ON ATMEL'S WEB SITE, ATMEL ASSUMES NO LIABILITY WHATSOEVER AND DISCLAIMS ANY EXPRESS, IMPLIED OR STATUTORY WARRANTY RELATING TO ITS PRODUCTS INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT. IN NO EVENT SHALL ATMEL BE LIABLE FOR ANY DIRECT, INDIRECT, CONSEQUENTIAL, PUNTIVE, SPECIAL OR INCIDEN-TAL DAMAGES (INCLUDING, WITHOUT LIMITATION, DAMAGES FOR LOSS OF PROFITS, BUSINESS INTERRUPTION, OR LOSS OF INFORMATION) ARISING OUT OF THE USE OR INABILITY TO USE THIS DOCUMENT, EVEN IF ATMEL HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. Atmel makes no representations or warranties with respect to the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and product descriptions at any time without notice. Atmel does not make any commitment to update the information contained herein. Unless specifically provided otherwise, Atmel products are not suitable for, and shall not be used in, automotive applications. Atmel's products are not intended, or warranted for use as components in applications intended to support or sustain life.

© Atmel Corporation 2005. All rights reserved. Atmel[®], logo and combinations thereof, Everywhere You Are[®] and others, are registered trademarks or trademarks of Atmel Corporation or its subsidiaries. Other terms and product names may be trademarks of others.

